

# SPI Bootloader for Hercules RM46 MCU

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#### **ABSTRACT**

This application report describes how to communicate with the Hercules<sup>™</sup> serial peripheral interface (SPI) bootloader. The SPI bootloader is a small piece of code that can be programmed at the beginning of Flash to act as an application loader as well as an update mechanism for applications running on a Hercules Cortex<sup>™</sup>-R4 based RM46 microcontroller.

Project collateral and source code discussed in this application report can be downloaded from the following URL: http://www.ti.com/lit/zip/spna195.

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# 1 Introduction

This application report describes how to work with and customize the Hercules sample bootloader application. The bootloader is a small piece of code that can be programmed at the beginning of Flash to act as an application loader as well as an update mechanism for an application running on a Hercules microcontroller. The default build of the bootloader is compiled to use the SPI2 interface for updating either the application or the bootloader. The bootloader is provided as source code, which allows any part of the bootloader to be completely customized. The bootloader was built and validated using Code Composer Studio™ v5 and the RM46 Hercules Development HDK.

A visual C++ project for the PC is provided to download an application via the bootloader.

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Table 1 shows an overview of the organization of the source code provided with the bootloader.

#### Table 1. List of Source Code Files Used in SPI Bootloader

bl_boot_eabi.asm	The start-up code used when the Code Composer Studio compiler is being used to build the bootloader.		
bl_check.c	The code to check whether a firmware update is required or not, or if a firmware update is being requested.		
bl_check.h	Prototypes for the update check code.		
bl_commands.h	The list of command and return messages supported by the bootloader.		
bl_config.h	Bootloader configuration file. This contains all of the possible configuration values.		
bl_flash.c	The functions for erasing, programming the Flash, and functions for erase and program check		
bl_flash.h	Prototypes for Flash operations		
bl_link.cmd	The linker script used when the Code Composer Studio compiler is being used to build the bootloader.		
bl_main.c	The main control loop of the bootloader.		
bl_packet.c	The functions for handling the packet processing of commands and responses.		
bl_packet.h	Prototypes for the packet handling functions.		
bl_spi.c	The functions for transferring data via the SPI2 port.		
bl_spi.h	Prototypes for the SPI2 transfer functions.		
bl_vimram.c	VIM RAM table definition and initialization		
bw_spi.c	The low-level SPI drive for transferring data		
bw_spi.h	Prototypes for the low-level SPI2 transfer functions.		
hw_gio.c	Low-level GIO driver		
hw_gio.h	Prototypes for low-level GIO driver		
hw_het.c	Low-level NHET driver		
hw_het.h	Prototypes for low-level NHET driver		
hw_interrupt_handler.c	Define the INT handlers		
hw_pinmux.c	Function for define the pinmux		
hw_pinmux.h	Prototypes for pinmux functions		
hw_sci.c	Low-level SCI driver		
hw_sci.h	Prototypes for low-level SCI driver		
hw_system.c	Initialize system registers and PLL		
startup_eabi.c	Global variables initialization		
sys_intvecs.asm	Interrupt vectors		
sys_svc.asm	Software INT routines		

#### 2 SPI Connections

The sample code provided with the bootloader supports updating via the SPI2 port, which is available on Hercules microcontrollers.

The SPI handling functions are SPISend() and SPIReceive(). The connections required to use the SPI port are the following four pins: SPI\_TX, SPI\_RX, SPI\_CIk, and SPI\_CS. The device communicating with the bootloader is responsible for driving the SPI\_RX, SPI\_CLK, and SPI\_CS pins, while the Hercules MCU drives the SPI\_TX pin. The format used for SPI communications is 8-bit data, clock polarity is 0 and clock phase is also set to 0.



www.ti.com Application Update

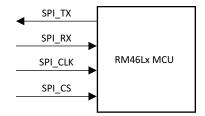


Figure 1. SPI Connections for RM46 Bootloader

## 3 Application Update

After HDK reset, the start-up code copies the bootloader from Flash to SRAM, branches to the copy of the bootloader in SRAM, and checks to see if an application update should be performed by calling *CheckForceUpdate()*. If an update is not required, the application is called.

The check for an application update consists of checking the magic word at 0x000017F0 and optionally checking the state of a GIO (GIOA Pin7 in the sample) pin. If either of these tests fail, then the application is assumed to be invalid and an update is forced. The GPIO pin check can be enabled with ENABLE\_UPDATE\_CHECK in the *bl\_config.h* header file, in which case an update can be forced by changing the state of a GPIO pin (with the push button S1 on HDK). If the application is valid and the GIO pin is not requesting an update, the application is called. Otherwise, an update is started by entering the main loop of the bootloader.

**Table 2. Application Update Options** 

	Invalid	Valid
Magic word at 0x000017F0	Other	0x5A5A5A5A
GIO pin	LOW	High

When performing an update via a SPI port, *ConfigureDevice()* is used to configure the selected SPI port, making it ready to be used to update the firmware. Then, *Updater()* sits in an endless loop accepting commands and updating the firmware when requested. All transmissions from this main routine use the packet handler functions (*SendPacket()*, *ReceivePacket()*, *AckPacket()*, and *NakPacket()*). Once the update is complete, the bootloader can be reset by issuing a reset command to the bootloader.

In the event that the bootloader itself needs to be updated, the bootloader must replace itself in Flash. An update of the bootloader is recognized by performing a download to address 0x0000,0000.

When a request to update the application comes through, the bootloader first erases the sector(s) for application before accepting the binary for the new application. Once all of the application Flash area has been successfully erased, the bootloader proceeds with the download of the new binary. After the application has been successfully programmed to the Flash, the bootloader will write "0x5A5A5A5A" to 0x000017F0.

In order for the bootloader to be separately erasable from the application, the applications must not be placed at the first sector, which is reserved for the bootloader. The default application start address in the sample code is 0x0002 0000.



Packet Handling www.ti.com

### 4 Packet Handling

All communications are done via defined packets that are acknowledged (ACK) or not Acknowledged (NAK) by the devices. The packets use the same format for receiving and sending packets. This includes the method used to acknowledge successful or unsuccessful reception of a packet. The basic packet format is shown in Figure 2.

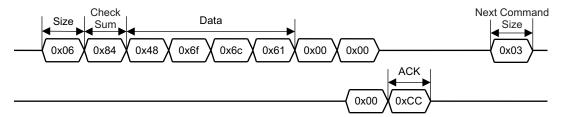


Figure 2. SPI Packet Format

The bootloader uses the <code>SendPacket()</code> function in order to send a packet of data to another device. This function encapsulates all of the steps necessary to send a valid packet to another device including waiting for the acknowledge or not-acknowledge from the other device. The following steps must be performed to successfully send a packet:

- Send out the size of the packet that will be sent to the device. The size is always the size of the data + 2.
- 2. Send out the checksum of the data buffer to help ensure proper transmission of the command. The checksum algorithm is implemented in the *CheckSum()* function provided and is simply a sum of the data bytes.
- 3. Send out the actual data bytes.
- 4. Wait for a single byte acknowledgment from the device that it either properly received the data or that it detected an error in the transmission.

Received packets use the same format as sent packets. The bootloader uses the *ReceivePacket()* function in order to receive or wait for a packet from another device. This function does not take care of acknowledging or not-acknowledging the packet to the other device. This allows the contents of the packet to be checked before sending back a response. The following steps must be performed to successfully receive a packet:

- Wait for non-zero data to be returned from the device. This is important as the device may send zero bytes between a sent and received data packet. The first non-zero byte received will be the size of the packet that is being received.
- 2. Read the next byte which will be the checksum for the packet.
- 3. Read the data bytes from the device. There will be packet size 2 bytes of data sent during the data phase. For example, if the packet size was 3, then there is only 1 byte of data to be received.
- 4. Calculate the checksum of the data bytes and ensure if it matches the checksum received in the packet.
- 5. Send an acknowledge or not-acknowledge to the device to indicate the successful or unsuccessful reception of the packet.

The steps necessary to acknowledge reception of a packet are implemented in the *AckPacket()* function. Acknowledge bytes are sent out whenever a packet is successfully received and verified by the bootloader.

A not-acknowledge byte is sent out whenever a sent packet is detected to have an error, usually as a result of a checksum error or just malformed data in the packet. This allows the sender to re-transmit the previous packet.

#### 5 Command Definitions

This section defines the list of commands that can be used when communicating with the SPI bootloader. The first byte of the data in a packet should always be one of the defined commands, followed by data or parameters as determined by the command that is sent.



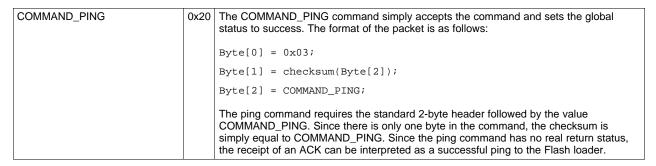
www.ti.com Command Definitions

The following two definitions are the values used to indicate successful or unsuccessful transmission of a packet:

#define COMMAND\_ACK 0x66
#define COMMAND\_NAK 0x33

The following tables and figures show the details of the commands used in SPI Bootloader.

#### Table 3. PING Command Definition for SPI Bootloader



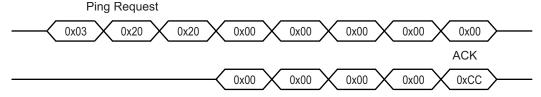
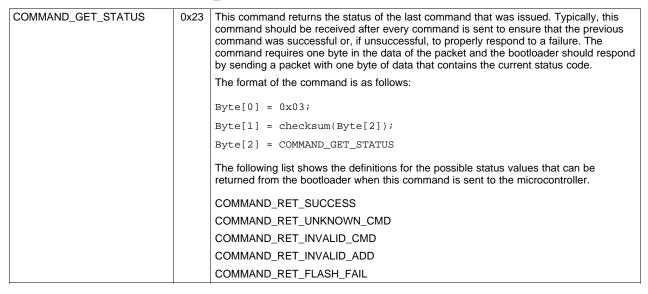


Figure 3. PING Command for SPI Bootloader

#### Table 4. GET\_Status Command Definition for SPI Bootloader



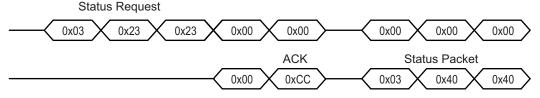


Figure 4. GET\_STATUS Command for SPI Bootloader



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# **Table 5. Other Command Definitions for SPI Bootloader**

Table 5. Other Command Definitions for SPI Bootloader				
COMMAND_DOWNLOAD	0x21	This command is sent to the bootloader to indicate where to store data and how many bytes will be sent by the COMMAND_SEND_DATA commands that follow. The command consists of two 32-bit values that are both transferred MSB first. The first 32-bit value is the address to start programming data into, while the second is the 32-bit size of the data that will be sent. This command also triggers an erasure of the full application area in the Flash or possibly the entire Flash depending on the address used. This causes the command to take longer to send the ACK/NAK in response to the command. This command should be followed by a COMMAND_GET_STATUS to ensure that the program address and program size were valid for the microcontroller running the bootloader.  The format of the command is as follows:		
		Byte[0] = 11		
		<pre>Byte[1] = checksum(Bytes[2:10])</pre>		
		Byte[2] = COMMAND_DOWNLOAD		
		Byte[3] = Program Address [31:24]		
		Byte[4] = Program Address [23:16]		
		Byte[5] = Program Address [15:8]		
		Byte[6] = Program Address [7:0]		
		Byte[7] = Program Size [31:24]		
		Byte[8] = Program Size [23:16]		
		Byte[9] = Program Size [15:8]		
COMMAND BUILD	0.00	Byte[10] = Program Size [7:0]		
COMMAND_RUN	0x22	This command is sent to the bootloader to transfer execution control to the specified address. The command is followed by a 32-bit value, transferred MSB first, that is the address to which the execution control is transferred.		
		The format of the command is as follows:		
		Byte[0] = 7		
		<pre>Byte[1] = checksum(Bytes[2:6])</pre>		
		Byte[2] = COMMAND_RUN		
		<pre>Byte[3] = Execute Address[31:24]</pre>		
		Byte[4] = Execute Address[23:16]		
		Byte[5] = Execute Address[15:8]		
		Byte[6] = Execute Address[7:0]		
COMMAND_GET_STATUS	0x23	This command returns the status of the last command that was issued. Typically, this command should be received after every command is sent to ensure that the previous command was successful or, if unsuccessful, to properly respond to a failure. The command requires one byte in the data of the packet and the bootloader should respond by sending a packet with one byte of data that contains the current status code.		
		The format of the command is as follows:		
		Byte[0] = 0x03;		
		<pre>Byte[1] = checksum(Byte[2]);</pre>		
		<pre>Byte[2] = COMMAND_GET_STATUS</pre>		
		The following list shows the definitions for the possible status values that can be returned from the bootloader when this command is sent to the microcontroller.		
		COMMAND_RET_SUCCESS		
		COMMAND_RET_UNKNOWN_CMD		
		COMMAND_RET_INVALID_CMD		
		COMMAND_RET_INVALID_ADD		
		COMMAND_RET_FLASH_FAIL		



www.ti.com Sample Code

# Table 5. Other Command Definitions for SPI Bootloader (continued)

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COMMAND_SEND_DATA	0x24	This command should only follow a COMMAND_DOWNLOAD command or another COMMAND_SEND_DATA command, if more data is needed. Consecutive send data commands automatically increment the address and continue programming from the previous location. The transfer size is limited by the size of the receive buffer in the bootloader (as configured by the BUFFER_SIZE parameter). The command terminates programming once the number of bytes indicated by the COMMAND_DOWNLOAD command has been received. Each time this function is called, it should be followed by a COMMAND_GET_STATUS command to ensure that the data was successfully programmed into the Flash. If the bootloader sends a NAK to this command, the bootloader will not increment the current address which allows for retransmission of the previous data.
		The format of the command is as follows:
		Byte[0] = 11
		Byte[1] = checksum(Bytes[2:10])
		Byte[2] = COMMAND_SEND_DATA
		Byte[3] = Data[0]
		Byte[4] = Data[1]
		Byte[5] = Data[2]
		Byte[6] = Data[3]
		Byte[7] = Data[4]
		Byte[8] = Data[5]
		Byte[9] = Data[6]
		Byte[10] = Data[7]
COMMAND_RESET	0x25	This command is used to tell the bootloader to reset. This is used after downloading a new image to the microcontroller to cause the new application or the new bootloader to start from a reset. The normal boot sequence occurs and the image runs as if from a hardware reset. It can also be used to reset the bootloader if a critical error occurs and the host device wants to restart communication with the bootloader. The bootloader responds with an ACK signal to the host device before actually executing the software reset on the microcontroller running the bootloader. This informs the updater application that the command was received successfully and the part will be reset.
		The format of the command is as follows:
		Byte[0] = 3
		Byte[1] = checksum(Byte[2])
		Byte[2] = COMMAND_RESET

# 6 Sample Code

The SPI bootloader Code Composer Studio v5.4 project and Visual C++ host project are available at: http://processors.wiki.ti.com/index.php/Category:RM4.

# 7 References

- RM46L852 16/32-Bit RISC Flash Microcontroller Data Manual (SPNS185)
- F021 Flash API Version 2.00.01 Reference Guide (SPNU501)
- Aardvark I2C/SPI Adaptor (V5.13) Data Sheet http://www.totalphase.com/products/aardvark\_i2cspi/

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